



**THE DATASHEET OF
TLV70028EVM-463**



Using the TLV700xxEVM-463

User's Guide



Literature Number: SLUU390
December 2009

TLV700xxEVM-463

This user's guide describes the characteristics, operation, and use of the TLV700xxEVM-463 evaluation module (EVM). This EVM demonstrates the Texas Instruments TLV700xx a low dropout (LDO) linear regulator that is capable of 200 mA at both fixed and adjustable output voltage levels. This user's guide includes setup instructions, a schematic diagram, thermal guidelines, a bill of materials, and printed-circuit board layout drawings for the EVM.

1 Introduction

The TLV700xxEVM-463 evaluation module (EVM) helps designers evaluate the operation and performance of the TLV700xx family. The TLV700xx is a 200-mA, low quiescent current, low noise, high PSRR, fast start-up LDO linear regulator with excellent line and load transient response.

2 Setup

This section describes the jumpers and connectors on the EVM as well as how to properly connect, setup, and use the TLV700xxEVM.

2.1 *Input/Output Connector Descriptions*

2.1.1 J1 –VIN

This is the positive input supply voltage. The leads to the input supply must be twisted and kept as short as possible to minimize EMI transmission. Additional bulk capacitance must be added between J1 and J2 if the supply leads are greater than six inches. An additional 47- μ F or greater capacitor improves the transient response of the TLV700xx and helps to reduce ringing on the input when long supply wires are used.

2.1.2 J2 –GND

This is the return connection for the input power supply of the regulator.

2.1.3 J3 –VOUT

This is the positive connection from the output. Connect this pin to the positive input of the load.

2.1.4 J4 –GND

This is the return connection for the output.

2.1.5 JP1 –ENABLE

This jumper enables or disables the regulator. Connecting the shorting jumper between pin 1 and pin 2 (ENABLE and VIN) enables the converter. Connecting the shorting jumper between pin 2 and pin 3 (ENABLE and GND) disables the converter. Never leave this pin floating.

2.2 Soldering Guidelines

Any soldering work on the TLV700xxEVM must be performed using a hot air system to avoid damaging the integrated circuit. A hot air system must be used when soldering or de-soldering any external components such as the feedback network as well as the device. A hot air system heats all of the traces on the board equally, which equalizes the thermal expansion of the traces on the board and thus reduces stress. Heating only one trace, such as with a soldering iron, allows one trace to expand more than the others and to cause shear stress on the pins of the QFN package. The shear stress on a single pin can be enough to break the pin of the device, thus causing a device failure.

3 Operation

This section provides information about the operation of the TLV700xxEVM.

3.1 Operation

Connect the positive input power supply to J1. Connect the input power return (ground) to J2. The TLV700xxEVM has an absolute maximum input voltage of 6 V. The recommended maximum operating voltage is 5.5 V. The actual highest input voltage may be less than 5.5 V due to thermal conditions. See the Thermal Considerations section of this manual to determine if the highest input voltage.

Connect the desired load between J3 (positive lead) and J4 (negative lead). Configure jumper JP1 as required. The function of JP1 is described in the Setup section (2.1.5) of this manual.

4 Thermal Guidelines

This section provides guidelines for the thermal management of the TLV700xxEVM-463 board.

4.1 Thermal Considerations

Thermal management is a key component of design of any power converter and is especially important when the power dissipation in the LDO is high. To better help you design the TLV700xx family into your application, use the following formula to approximate the maximum power dissipation at a particular ambient temperature:

$$T_J = T_A + P_d \times \theta_{JA} \quad (1)$$

where T_J is the junction temperature, T_A is the ambient temperature, P_d is the power dissipation in the device, and θ_{JA} is the thermal resistance from junction to ambient. All temperatures are in degrees Celsius.

The thermal resistance from junction to ambient for the TLV700xxEVM has a typical value of 206°C/W. The recommended maximum operating junction temperature specified in the data sheet for the TLV700xx family is 125°C. With these two pieces of information, the maximum power dissipation can be found by using [Equation 1](#).

Example Calculation:

For example, what is the maximum input voltage that can be applied to a TLV700XX (fixed 2.5-V output) if the ambient temperature is 85°C and the full 200 mA of load current is required?

$$T_J = 125^\circ\text{C}, T_A = 85^\circ\text{C}, \theta_{JA} = 206^\circ\text{C/W} \quad (2)$$

Using [Equation 1](#), substitute in the preceding given values and find that the maximum power dissipation for the part is $P_d = 0.194$ W.

$$125^\circ\text{C} = 85^\circ\text{C} + P_d (206^\circ\text{C/W}) \quad (3)$$

This means that the total power dissipation of the TLV700xx must be less than 0.194 W. Now, the input voltage can be calculated.

$$P_d = (V_{IN} - V_{OUT}) \times I_{OUT} = (V_{IN} - 2.8)(200 \times 10^{-3}) = 0.194 \text{ W} \quad (4)$$

So, the maximum input voltage needs to be 3.77 V or less in order to maintain a safe junction temperature.

Similar analysis can be performed to determine the maximum ambient temperature over a range of operation. For an input voltage of 3.3 V you can calculate the highest ambient temperature allowed and still provide full output current.

Using [Equation 1](#) and [Equation 3](#) again, T_A is 93.0°C.

5 Board Layout

This section provides the TLV700xxEVM-463 board layout and illustrations

5.1 Layout

When laying out the board for the TLV700xx, TI recommends that the board be designed with separate ground planes for V_{in} and V_{out} which are only connected at the GND pin of the device. Also, the ground connection for the bypass capacitor must be connected directly to the GND pin of the device. By following the foregoing two guidelines, you can improve the PSRR performance of the TLV700xx. See the TLV700xx data sheet for specific layout guidelines.

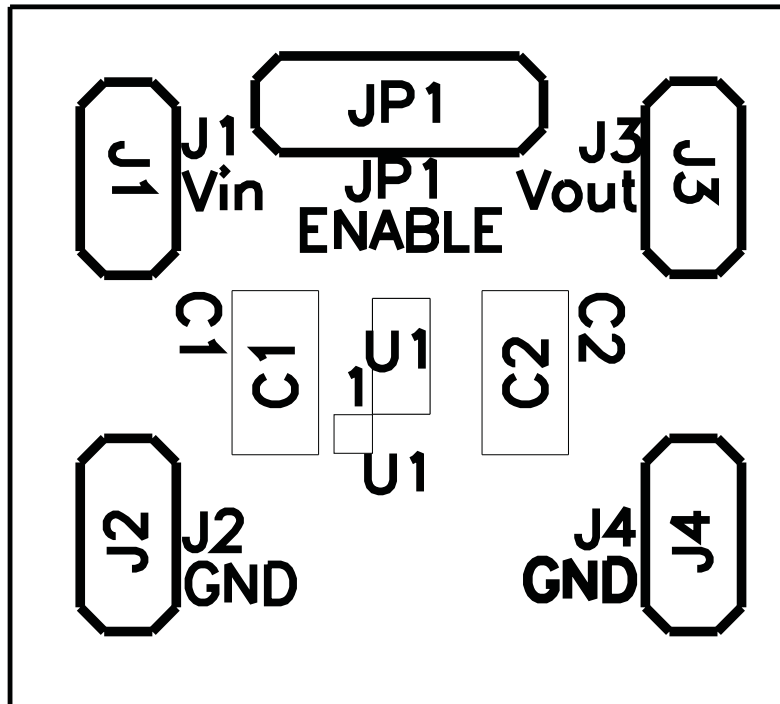


Figure 1. Assembly Layer

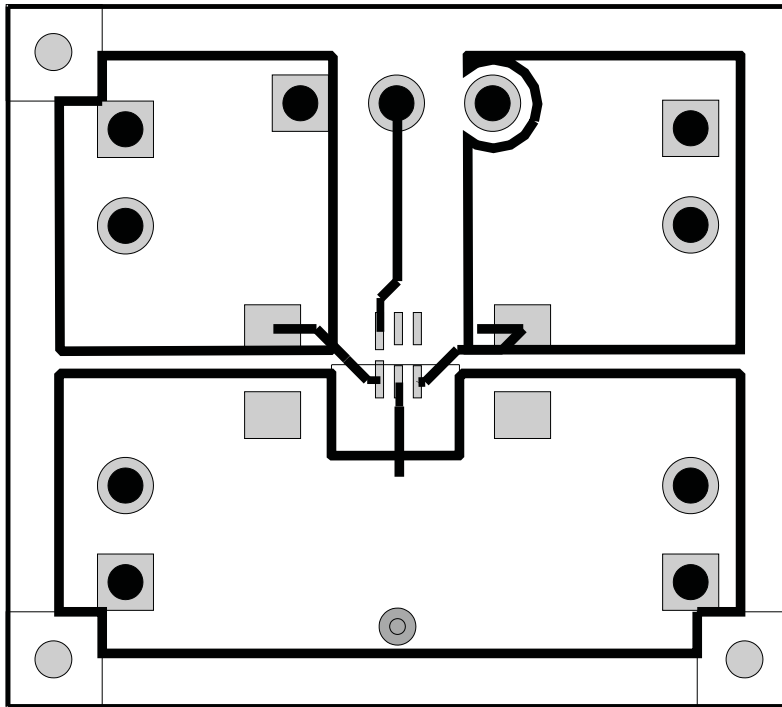


Figure 2. Top Layer Routing

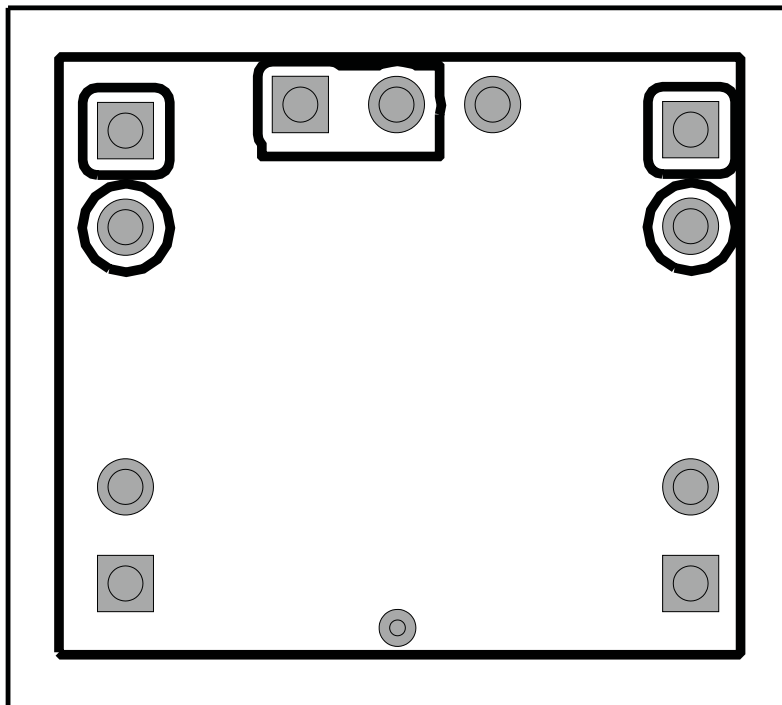


Figure 3. Bottom Layer Routing

6 Schematic and List of Materials

This section provides the TLV700xxEVM-463 schematic and List of materials.

6.1 Schematic

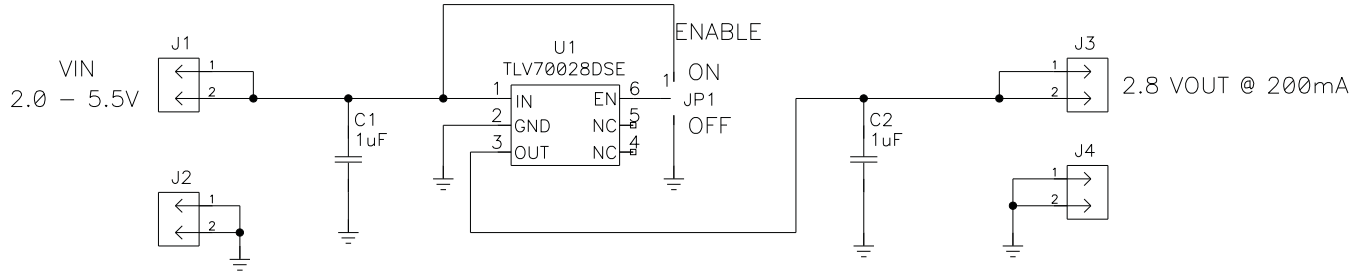


Figure 4. TLV700xxEVM-463 Schematic

6.2 List of Materials

Table 1. TLV700xxEVM-463 List of Materials

COUNT	REF DES	DESCRIPTION	PART NUMBER	MFR
2	C1, C2	Capacitor, ceramic, 25 V, X5R, 20%, 1 µF, 805	STD	STD
4	J1, J2, J3, J4	Header, 2 pin, 100-mil spacing, 0.100 in x 2 in	PEC02SAAN	Sullins
1	JP1	Header, 3 pin, 100-mil spacing, 0.100 in x 3 in	PEC03SAAN	Sullins
1	U1	200 mA, low IQ, LDO regulator, SON-6	TLV70028DSE	TI
1	--	Shunt, 100 mil, black, 0.1	929950-00	3M
1	--	PCB, 0.815 in x 0.725 in x 0.062 in	HPA463	Any

EVALUATION BOARD/KIT IMPORTANT NOTICE

Texas Instruments (TI) provides the enclosed product(s) under the following conditions:

This evaluation board/kit is intended for use for **ENGINEERING DEVELOPMENT, DEMONSTRATION, OR EVALUATION PURPOSES ONLY** and is not considered by TI to be a finished end-product fit for general consumer use. Persons handling the product(s) must have electronics training and observe good engineering practice standards. As such, the goods being provided are not intended to be complete in terms of required design-, marketing-, and/or manufacturing-related protective considerations, including product safety and environmental measures typically found in end products that incorporate such semiconductor components or circuit boards. This evaluation board/kit does not fall within the scope of the European Union directives regarding electromagnetic compatibility, restricted substances (RoHS), recycling (WEEE), FCC, CE or UL, and therefore may not meet the technical requirements of these directives or other related directives.

Should this evaluation board/kit not meet the specifications indicated in the User's Guide, the board/kit may be returned within 30 days from the date of delivery for a full refund. **THE FOREGOING WARRANTY IS THE EXCLUSIVE WARRANTY MADE BY SELLER TO BUYER AND IS IN LIEU OF ALL OTHER WARRANTIES, EXPRESSED, IMPLIED, OR STATUTORY, INCLUDING ANY WARRANTY OF MERCHANTABILITY OR FITNESS FOR ANY PARTICULAR PURPOSE.**

The user assumes all responsibility and liability for proper and safe handling of the goods. Further, the user indemnifies TI from all claims arising from the handling or use of the goods. Due to the open construction of the product, it is the user's responsibility to take any and all appropriate precautions with regard to electrostatic discharge.

EXCEPT TO THE EXTENT OF THE INDEMNITY SET FORTH ABOVE, NEITHER PARTY SHALL BE LIABLE TO THE OTHER FOR ANY INDIRECT, SPECIAL, INCIDENTAL, OR CONSEQUENTIAL DAMAGES.

TI currently deals with a variety of customers for products, and therefore our arrangement with the user **is not exclusive**.

TI assumes **no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein.**

Please read the User's Guide and, specifically, the Warnings and Restrictions notice in the User's Guide prior to handling the product. This notice contains important safety information about temperatures and voltages. For additional information on TI's environmental and/or safety programs, please contact the TI application engineer or visit www.ti.com/esh.

No license is granted under any patent right or other intellectual property right of TI covering or relating to any machine, process, or combination in which such TI products or services might be or are used.

FCC Warning

This evaluation board/kit is intended for use for **ENGINEERING DEVELOPMENT, DEMONSTRATION, OR EVALUATION PURPOSES ONLY** and is not considered by TI to be a finished end-product fit for general consumer use. It generates, uses, and can radiate radio frequency energy and has not been tested for compliance with the limits of computing devices pursuant to part 15 of FCC rules, which are designed to provide reasonable protection against radio frequency interference. Operation of this equipment in other environments may cause interference with radio communications, in which case the user at his own expense will be required to take whatever measures may be required to correct this interference.

EVM WARNINGS AND RESTRICTIONS

It is important to operate this EVM within the input voltage range of 2.0 V to 5.5 V and the output voltage range of 0.8 V to 5.5 V.

Exceeding the specified input range may cause unexpected operation and/or irreversible damage to the EVM. If there are questions concerning the input range, please contact a TI field representative prior to connecting the input power.

Applying loads outside of the specified output range may result in unintended operation and/or possible permanent damage to the EVM. Please consult the EVM User's Guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative.

During normal operation, some circuit components may have case temperatures greater than 85°C. The EVM is designed to operate properly with certain components above 85°C as long as the input and output ranges are maintained. These components include but are not limited to linear regulators, switching transistors, pass transistors, and current sense resistors. These types of devices can be identified using the EVM schematic located in the EVM User's Guide. When placing measurement probes near these devices during operation, please be aware that these devices may be very warm to the touch.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2009, Texas Instruments Incorporated

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
RF/IF and ZigBee® Solutions	www.ti.com/lprf

Applications

Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2009, Texas Instruments Incorporated

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

 [View TLV70028EVM-463 on WIN SOURCE](#)

 [Texas Instruments](#) Information

Optimize Your Supply Chain with WIN SOURCE Solutions

-  Global Sourcing Solution
-  Obsolete Management
-  Cost Control Management
-  Shortage Management
-  Alternative Solution
-  Excess Inventory Management